

CORNING LOTUS[™] NXT GLASS FOR HIGH-PERFORMANCE DISPLAYS

Corning Lotus[™] NXT Glass is specially formulated for high-temperature processing. By working in close collaboration with its customers, Corning developed a new substrate that withstands the demanding processes involved in creating high-performance displays.

Lotus NXT Glass is the newest addition to Corning's specialty glass platform. It is formulated to perform exceptionally well in low temperature poly-silicon (LTPS) and oxide thin-film transistor (TFT) backplane manufacturing processes.

Specifically, Lotus NXT Glass provides industry-leading levels of low total pitch variation resulting in heightened resolutions; more energy-efficient displays; and better yields.

PRODUCT & MATERIAL INFORMATION

PRODUCT SPECIFICATIONS Maximum Size Gen 10 Substrate **Major Thicknesses** 0.3 mm, 0.4 mm, 0.5 mm, 0.6 mm, 0.7 mm **Thickness Tolerance** ± 0.02 mm **Thickness Ranges** ≤ 9 µm (150mm Moving Window) **Edges R**-Beveled **Corner Cuts** 1.5 ± 1.0 mm **Orientation Corner(s)** Various **Squareness** ± 0.3 mm Sheet Warp ≤ 0.20 mm Cut off: 0.8-8 mm ≤ 0.06 µm Waviness Cut off: 0.8-25 mm ≤ 0.33 µm SUBSTRATE INSPECTION & PACKAGING Scratch & Stain Pattern Surface None visible using 5K lux or 10K lux

Lotus NXT Glass is produced to the following typical specifications:

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	Back Surface	1.5K or 5K Limit Sample using 1.5K lux			
Inclusions	≤ 0.1 mm				
Edge Chips	≤ 1.0 mm				
Edge Cracks	None visible using 1.5K lux				
Packaging	Polypropylene Slotted Cases (=<730 x 920mm)				
Tackaying	Corning [®] DensePak [®] (products larger than 730 x 920 mm)				
Quality Area	Scratch, stain and inclusion fault criteria apply to all except a border area on each substrate which has a width of 10 mm.				

DIMENSIONAL MEASUREMENT									
	Size	Thickness	Chamfer	Corner Cut	Orientation Corner	Squareness	Warp	Waviness	Compaction Variation
Laser Gauge	x	х				х			
Calipers	х								
Micrometer		х							
Scale Loupe			Х	Х	x				
Squareness Gauge						Х			
Warp Gauge							х		
Profilometer								х	
Compaction Gauge									Х

VISUAL INSPECTION						
	Pattern Surface	Back Surface	Inclusions	Chips	Cracks	
Environment		Darke	ened Clean Roo	om		
Light Source	Halogen (10K lux), Halogen (5K lux) or Fluorescent (1.5K lux)					
Brightness	5K or 10K lux	1.5K lux	1.5K lux	1.5K lux	1.5K lux	
Method	Automated					

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	MATERIAL INFORMATION	N		
Glass Type	Alkaline Earth Boro-Aluminosilicate			
Forms Available	Fusion Drawn Sheet			
Principle Uses	Substrates for High Performance Displays with LTPS and oxide- TFT technologies.			
	Density (20°C)	2.59 g/cm ³		
	Young's Modulus	83 GPa		
Mechanical Properties	Shear Modulus	34 GPa		
	Poisson's Ratio	0.23		
	Vickers Hardness (200g load, 15 sec dwell)	643 kgf/mm2		
Thermal Expansion	Coefficient of Thermal Expansion (0 - 300°C)	35 x 10 ⁻⁷ /°C		
	Softening Point (10 ^{7.6} poises)	1043°C		
Viscosity	Annealing Point (10 ¹³ poises)	806°C		
	Strain Point (10 ^{14.5} poises)	752°C		
		at 25°C	25.7 ohm-cm	
	Log ₁₀ Volume Resistivity	at 250°C	14.3 ohm-cm	
Flootnicel Dressentice		at 500°C	9.4 ohm-cm	
Electrical Properties	Dielectric Constant (20°C, 1kHz)	6.17		
	Loss Tangent (20°C, 1kHz)	0.15%		
	Refractive Index (at 589.3nm)	1.526		
Ontical Properties	Dispersion Constant	61.7		
	Birefringence Constant	283 (nm/cm)/(kg/mm ²)		
	Transmittance (from 400 to 800nm)	>90%		

THERMAL CONDUCTIVITY

Thermal conductivity is a calculated value, and is equal to the product of the Thermal diffusivity multiplied by specific heat multiplied by density of the glass.

Temp (°C)	Specific Heat (J/g-K)	Thermal Diffusivity (cm ² /sec)	Thermal Conductivity (W/cm-K)
23	0.759	0.0061	0.0116
100	0.820	0.0060	0.0130
200	0.903	0.0057	0.0137
300	0.965	0.0057	0.0150
400	1.010	0.0056	0.0159
500	1.044	0.0056	0.0159

CHEMICAL DURABILITY

Chemical durability is measured via weight loss per surface area after immersion. Values are highly dependent upon actual testing conditions. Unless otherwise noted, concentrations refer to weight percent.

Reagents	Time	Temp	Weight Loss (mg/cm ²)
HCI - 5%	24 hrs	95°C	0.04
HNO ₃ - 1M	24 hrs	95°C	0.03
HF - 10%	20 min	20°C	5.81
110BHF	5 min	30°C	0.34
1HF:10HNO ₃	3 min	20°C	1.67
1HF:100HNO ₃	3 min	20°C	0.17
DI H ₂ O	24 hrs	95°C	0.00
Na ₂ CO ₃ - 0.02N	6 hrs	95°C	0.10
NaOH - 5%	6 hrs	95°C	1.46